

Abstract

The present invention is a method of evaluating a shape of a semiconductor wafer comprising the steps of: measuring shape data of a semiconductor wafer by scanning a front surface and/or a back surface of the semiconductor wafer; calculating a differential profile through a differential process of the measured shape data; analyzing the obtained differential profile and obtaining a surface characteristic of the wafer, and; evaluating a shape of the semiconductor wafer. Thereby, there are provided a method of evaluating a shape of a semiconductor wafer and an apparatus for evaluating a shape thereof, wherein a shape of a semiconductor wafer, particularly a shape of a peripheral portion of the wafer, can be quantitatively evaluated from a viewpoint different from conventional SFQR etc., and the shape quality of the wafer can be accurately evaluated over a specification of a strict design rule.